

Siconnex BATCHSPRAY® Technology.



Our innovative BATCHSPRAY® technology is based on a closed system, in which wet chemical cleaning and etching processes are performed highly efficiently. Various chemical processes, including rinsing and drying, are performed fully automatically in a process chamber.



ADVANTAGES

- Automated dry-in, dry-out process
- High throughput, due to 25 or 50 wafer chamber
- Small footprint (~ 25 sqft)
- For 2" to 12" substrates
- Manual or automated robot loading with the patented Retainer Comb Handling (RCH) System (FOUP, SMIF, etc. compatible)



BATCHSPRAY®
ACID



BATCHSPRAY®
SOLVENT



BATCHSPRAY®
Autoload

**RETAINER
COMB
HANDLING**

a patent by
siconnex



BATCHSPRAY®
CLEAN Autoload

PROCESS APPLICATIONS
with our BATCHSPRAY® systems:



ETCH



CLEAN



RESIST STRIP

Siconnex BATCHSPRAY® at a glance.



BATCHSPRAY®

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